

Chao-hong Wang

List of Publications by Year in descending order

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61
papers

1,369
citations

304368

22
h-index

360668

35
g-index

62
all docs

62
docs citations

62
times ranked

586
citing authors

#	ARTICLE	IF	CITATIONS
1	Phase equilibria and solidification properties of Sn-Cu-Ni alloys. <i>Journal of Electronic Materials</i> , 2002, 31, 907-915.	1.0	156
2	Phase Diagrams of Pb-Free Solders and their Related Materials Systems. <i>Journal of Materials Science: Materials in Electronics</i> , 2006, 18, 19-37.	1.1	83
3	Sn/Co solid/solid interfacial reactions. <i>Intermetallics</i> , 2008, 16, 524-530.	1.8	66
4	Effects of Ni addition on the interfacial reactions between Sn-Cu solders and Ni substrate. <i>Intermetallics</i> , 2010, 18, 616-622.	1.8	50
5	Effects of current density and temperature on Sn/Ni interfacial reactions under current stressing. <i>Intermetallics</i> , 2011, 19, 75-80.	1.8	49
6	Temperature effects on liquid-state Sn/Co interfacial reactions. <i>Intermetallics</i> , 2013, 32, 57-63.	1.8	46
7	Effects of Zn and Ga Additions to Suppress PdSn ₄ Growth at a Solder/Pd Interface Under Current Stressing. <i>Journal of Electronic Materials</i> , 2018, 47, 1-8.	1.0	46
8	Interfacial reactions of Sn-Cu/Ni couples at 250 °C. <i>Journal of Materials Research</i> , 2006, 21, 2270-2277.	1.2	45
9	Kinetic analysis of Ni ₅ Zn ₂₁ growth at the interface between Sn-Zn solders and Ni. <i>Intermetallics</i> , 2012, 22, 166-175.	1.8	40
10	Study of the Effects of Zn Content on the Interfacial Reactions Between Sn-Zn Solders and Ni Substrates at 250 °C. <i>Journal of Electronic Materials</i> , 2010, 39, 2375-2381.	1.0	39
11	Solid-state interfacial reactions of Sn and Sn-Ag-Cu solders with an electroless Co(P) layer deposited on a Cu substrate. <i>Journal of Alloys and Compounds</i> , 2016, 662, 475-483.	2.8	39
12	Growth kinetics of the solid-state interfacial reactions in the Sn-Cu/Co and Sn/Co-Cu couples. <i>Materials Chemistry and Physics</i> , 2011, 130, 651-656.	2.0	38
13	Lowering of Sn-Sb alloy melting points caused by substrate dissolution. <i>Journal of Electronic Materials</i> , 2006, 35, 1982-1985.	1.0	37
14	Phase equilibria of Sn-Sb-Cu system. <i>Materials Chemistry and Physics</i> , 2012, 132, 703-715.	2.0	36
15	Effects of electromigration on interfacial reactions in cast Sn/Cu joints. <i>Journal of Materials Research</i> , 2007, 22, 695-702.	1.2	34
16	Interfacial Reactions in the Sn-Bi/Te Couples. <i>Journal of Electronic Materials</i> , 2008, 37, 40-44.	1.0	34
17	Interfacial reactions in the Sn-Sb/Ag and Sn-Sb/Cu couples. <i>Materials Chemistry and Physics</i> , 2008, 111, 17-19.	2.0	32
18	Influence of the P content on phase formation in the interfacial reactions between Sn and electroless Co(P) metallization on Cu substrate. <i>Journal of Alloys and Compounds</i> , 2015, 619, 474-480.	2.8	29

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19	Cruciform pattern formation in Sn/Co couples. <i>Journal of Materials Research</i> , 2007, 22, 3404-3409.	1.2	28
20	Interfacial reactions between eutectic Sn-Pb solder and Co substrate. <i>Journal of Materials Science</i> , 2011, 46, 2654-2661.	1.7	28
21	Inhibiting CoSn ₃ growth at the Sn/Co system by minor Zn addition. <i>Intermetallics</i> , 2015, 56, 68-74.	1.8	28
22	Phase equilibria of the ternary Al-Cu-Ni system and interfacial reactions of related systems at 800 °C. <i>Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science</i> , 2003, 34, 199-209.	1.1	25
23	Effects of Minor Amounts of Zn on the Sn-Zn/Ni Interfacial Reactions and Phase Equilibria of the Ternary Sn-Zn-Ni System at 250 °C. <i>Journal of Electronic Materials</i> , 2011, 40, 2436-2444.	1.0	22
24	Peltier Effect on Sn/Co Interfacial Reactions. <i>Journal of Electronic Materials</i> , 2009, 38, 655-662.	1.0	19
25	Enhanced growth of the Ni ₃ Sn ₄ phase at the Sn/Ni interface subjected to strains. <i>Scripta Materialia</i> , 2011, 65, 691-694.	2.6	19
26	Isothermal section of the ternary Sn-Cu-Ni system and interfacial reactions in the Sn-Cu/Ni couples at 800 °C. <i>Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science</i> , 2003, 34, 2281-2287.	1.1	17
27	Effective suppression of electromigration-induced Cu dissolution by using Ag as a barrier layer in lead-free solder joints. <i>Journal of Alloys and Compounds</i> , 2013, 564, 35-41.	2.8	17
28	Coupling Effect of the Interfacial Reaction in Co/Sn/Cu Diffusion Couples. <i>Journal of Electronic Materials</i> , 2010, 39, 1303-1308.	1.0	15
29	Effects of Sn thickness on morphology and evolution of Ni ₃ Sn ₄ grains formed between molten Sn and Ni substrate. <i>Intermetallics</i> , 2015, 61, 9-15.	1.8	15
30	Strong effects of minor Ga addition on liquid-state Sn-Ga/Co interfacial reactions. <i>Journal of Alloys and Compounds</i> , 2015, 649, 1197-1204.	2.8	15
31	Phase transformation and microstructural evolution in solder joints. <i>Jom</i> , 2007, 59, 39-43.	0.9	14
32	Interfacial reactions of high-temperature Zn-Sn solders with Ni substrate. <i>Materials Chemistry and Physics</i> , 2012, 136, 325-333.	2.0	14
33	Study of electromigration resistance of (Pd,Ni)Sn ₄ phase in lead-free solder joints. <i>Journal of Alloys and Compounds</i> , 2016, 654, 546-553.	2.8	14
34	Interfacial reactions in Sn-(Cu)/Cu ₆ Sn ₅ /Ni couples at 210 °C. <i>Intermetallics</i> , 2008, 16, 531-537.	1.8	13
35	Kinetic study of solid-state interfacial reactions of p-type (Bi,Sb) ₂ Te ₃ thermoelectric materials with Sn and Sn-Ag-Cu solders. <i>Journal of Alloys and Compounds</i> , 2018, 767, 1133-1140.	2.8	13
36	Pseudocapacitive performance of Co(OH) ₂ enhanced by Ni(OH) ₂ formation on porous Ni/Cu electrode. <i>Electrochimica Acta</i> , 2015, 182, 47-60.	2.6	12

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37	Metastable CoSn ₄ formation induced by minor Ga addition and effective suppression effect on the IMC growth in solid-state Sn–Ga/Co reactions. <i>Journal of Materials Science</i> , 2016, 51, 7309-7321.	1.7	12
38	Dissolution and Interfacial Reactions of (Cu,Ni) ₆ Sn ₅ Intermetallic Compound in Molten Sn-Cu-Ni Solders. <i>Journal of Electronic Materials</i> , 2014, 43, 195-203.	1.0	11
39	Microstructure evolution of Ni ₅ Zn ₂₁ intermetallic compound at Sn–9wt%Zn/Ni interface. <i>Materials Chemistry and Physics</i> , 2013, 138, 937-943.	2.0	10
40	Minor P Doping to Effectively Suppress IMC Growth in Solder Joints with Electroplated Co(P) Metallization. <i>Journal of Electronic Materials</i> , 2019, 48, 4552-4561.	1.0	10
41	Phase Equilibria of the Sn-Sb-Ag Ternary System (I): Experimental. <i>Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science</i> , 2008, 39, 3191-3198.	1.1	9
42	Liquid-State Interfacial Reactions of Sn-Zn/Co Couples at 250°C. <i>Journal of Electronic Materials</i> , 2012, 41, 3259-3265.	1.0	9
43	Peltier effect on CoSn ₃ growth in Sn/Co/Sn couples with different substrate lengths. <i>Materials Chemistry and Physics</i> , 2015, 153, 72-77.	2.0	9
44	Phase diagram of Bi–In–Se ternary system. <i>Calphad: Computer Coupling of Phase Diagrams and Thermochemistry</i> , 2020, 68, 101744.	0.7	9
45	Minor Ga addition to effectively inhibit PdSn ₄ growth between Sn solder and Pd substrate. <i>Intermetallics</i> , 2015, 67, 102-110.	1.8	8
46	Liquid-state interfacial reactions in Sn–Zn/Pd couples and phase equilibria of the Sn–Zn–Pd system at 260°C. <i>Intermetallics</i> , 2015, 59, 68-74.	1.8	6
47	Phase Equilibria of the Ternary Sn-Pb-Co System at 250°C and Interfacial Reactions of Co with Sn-Pb Alloys. <i>Journal of Electronic Materials</i> , 2015, 44, 4567-4575.	1.0	6
48	Cruciform Pattern of Ni ₅ Zn ₂₁ Formed in Interfacial Reactions Between Ni and Sn–Zn Solders. <i>Journal of Electronic Materials</i> , 2014, 43, 1362-1369.	1.0	5
49	Growth kinetics and mechanism of Pd ₂ Zn ₉ at the interface of Pd substrate with molten Sn–9wt.%Zn solder. <i>Materials Chemistry and Physics</i> , 2015, 164, 223-229.	2.0	5
50	Effects of Minor Cu, Ni and Ag Additions on the Reactions Between Sn-Based Solders and Co Substrate. <i>Jom</i> , 2019, 71, 3023-3030.	0.9	5
51	Liquid-State Interfacial Reactions of Sn and Sn-Ag-Cu Solders with p-Type (Bi,Sb) ₂ Te ₃ Thermoelectric Material. <i>Jom</i> , 2020, 72, 3558-3566.	0.9	4
52	Phase equilibria of the ternary Ni-Cr-Zr system and interfacial reactions in the Ni-Cr/Zr couples. <i>Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science</i> , 2002, 33, 995-1002.	1.1	3
53	Phase Equilibria of the Ternary Sn-Zn-Co System at 250°C and 500°C. <i>Journal of Electronic Materials</i> , 2015, 44, 4907-4919.	1.0	3
54	Effects of Ga Addition on Interfacial Reactions Between Sn-Based Solders and Ni. <i>Journal of Electronic Materials</i> , 2016, 45, 6200-6207.	1.0	3

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55	Investigations on interfacial reactions at reentrant corners. Journal of Materials Research, 2010, 25, 999-1003.	1.2	2
56	Interfacial Microstructure Evolution Between Sn-Zn Solders and Ag Substrate During Solid-State Annealing. Journal of Electronic Materials, 2014, 43, 4594-4601.	1.0	2
57	Interfacial reactions in In/Ag ₂ Se couples. Materials Chemistry and Physics, 2015, 162, 11-14.	2.0	2
58	Liquidus Projection and Thermodynamic Modeling of a Sn-Ag-Zn System. Journal of Electronic Materials, 2017, 46, 6910-6921.	1.0	2
59	Minor Ge Addition to Suppress the IMC Growth in Interfacial Reactions of Co with Sn-Ag-Ge and Sn-Ag-Cu-Ge Solders. Journal of Electronic Materials, 2022, 51, 1820-1830.	1.0	2
60	Ag Whisker Formation in Ag-In-Se Alloys. Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science, 2013, 44, 5281-5283.	1.1	1
61	Reaction mechanism for liquid-state interfacial reactions of Co with In and eutectic In-48at.%Sn solders. Journal of Materials Science: Materials in Electronics, 2022, 33, 12321.	1.1	0